

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

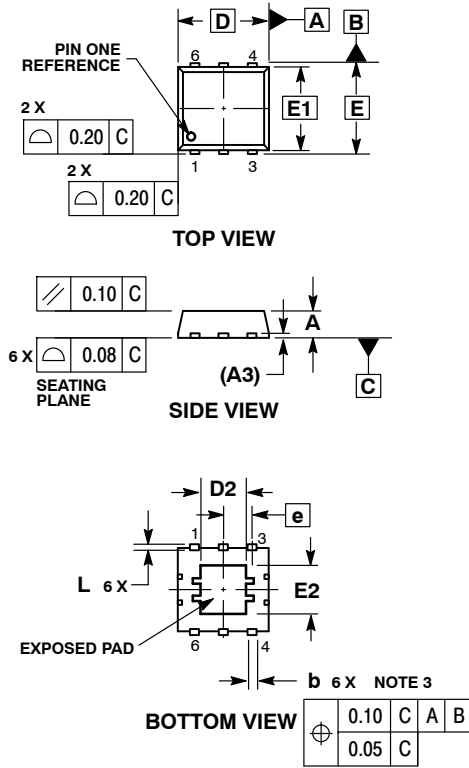
ON Semiconductor®



SCALE 2:1

HSON-6
CASE 506AE-01
ISSUE A

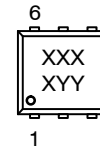
DATE 26 JAN 2005



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.15 MM FROM TERMINAL.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.90
A3	0.15 REF	
b	0.20	0.40
D	2.90 BSC	
D2	1.40	1.60
E	3.00 BSC	
E1	2.80 BSC	
E2	1.50	1.70
e	0.95 BSC	
L	0.15	0.25

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
YY = Wafer Lot

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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DESCRIPTION:	HSO N-6, 2.9 X 3.0 MM, 0.95 MM PITCH	PAGE 1 OF 1

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